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ABSTRACT

An integrated circuit array structure (10) is disclosed which comprises an electrically conductive leadframe (14), encapsulant material (26) disposed over the electrically conductive leadframe (14), and a plurality of integrated circuit die pads (16) disposed between the encapsulant material (26) and the electrically conductive leadframe (14). The electrically conductive leadframe (14) and the die pads (16) are arranged so as to form a plurality of contiguous integrated circuit packages (12), and the electrically conductive leadframe (14) includes at least one discontinuous portion (22, 24) disposed adjacent the periphery (23) of at least one integrated circuit package (12) and arranged so as to cause engagement of the electrically conductive leadframe (14) with the encapsulant material (26) and thereby restriction of delamination of the encapsulant material (26) from the electrically conductive leadframe (14) during singulation of integrated circuit packages (12) from the integrated circuit array structure (10). A corresponding method of manufacturing integrated circuit packages is also disclosed.

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